

HUF75652G3-VB Datasheet N-Channel 100 V (D-S) 175 °C MOSFET

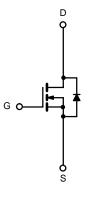
PRODUCT SUMMARY			
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)	
100	0.006 at V _{GS} = 10 V	150	

FEATURES

- Trench Power MOSFET
- New Package with Low Thermal Resistance
- 100 % R_g Tested







N-Channel MOSFET

ABSOLUTE MAXIMUM RATING	GS T _C = 25 °C, unless ot	herwise noted			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	100	M		
Gate-Source Voltage	V _{GS}	± 20	V		
Continuous Drain Current ($T_1 = 175 ^{\circ}C$)	T _C = 25 °C		150	А	
$Continuous Drain Current (T_j = 175 C)$	T _C = 125 °C	I _D	100 ^a		
Pulsed Drain Current	I _{DM}	600			
Avalanche Current	I _{AR}	75	1		
Repetitive Avalanche Energy ^b	L = 0.1 mH	E _{AR}	280	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	P	375 ^c	W	
maximum Power Dissipation*	T _A = 25 °C		3.75		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	TO-247	R _{thJA}	40	°C/W	
Junction-to-Case (Drain)		R _{thJC}	0.5	C/VV	

Notes:

a. Package limited.

b. Duty cycle \leq 1 %. c. See SOA curve for voltage derating.

SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	-						
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	100			N	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	2		4	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		V _{DS} = 100 V, V _{GS} = 0 V			1	μA	
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = 100 V, V_{GS} = 0 V, T_{J} = 125 °C			50		
		V_{DS} = 100 V, V_{GS} = 0 V, T_{J} = 175 °C			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	120			А	
		V _{GS} = 10 V, I _D = 30 A		0.006			
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 30 A, T _J = 125 °C		0.017		Ω	
		V _{GS} = 10 V, I _D = 30 A, T _J = 175 °C		0.025			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A	25			S	
Dynamic ^b							
Input Capacitance	C _{iss}			6700		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		750			
Reverse Transfer Capacitance	C _{rss}			280			
Total Gate Charge ^c	Qg			110	160	nC	
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 50 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 85 \text{ A}$		24			
Gate-Drain Charge ^c	Q _{gd}			24			
Gate Resistance	Rg		1.0		6.2	Ω	
Turn-On Delay Time ^c	t _{d(on)}			20	30	ns	
Rise Time ^c	t _r	$V_{\text{DD}} = 50 \text{ V}, \text{ R}_{\text{L}} = 0.6 \Omega$ $\text{I}_{\text{D}} \cong 85 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 2.5 \Omega$		125	200		
Turn-Off Delay Time ^c	t _{d(off)}			55	85		
Fall Time ^c	t _f			130	195		
Source-Drain Diode Ratings and Ch	aracteristics 7	$\Gamma_{\rm C} = 25 \ {}^{\circ}{\rm C}^{\rm b}$	•	•	•	•	
Continuous Current	۱ _S			110	•		
Pulsed Current	I _{SM}				240	A	
Forward Voltage ^a	V _{SD}	$I_{F} = 85 \text{ A}, V_{GS} = 0 \text{ V}$		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			70	140	ns	
Peak Reverse Recovery Charge	I _{RM(REC)}	I _F = 50 A, dl/dt = 100 A/μs		5.5	10	А	
Reverse Recovery Charge	Q _{rr}			0.19	0.35	μC	

Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

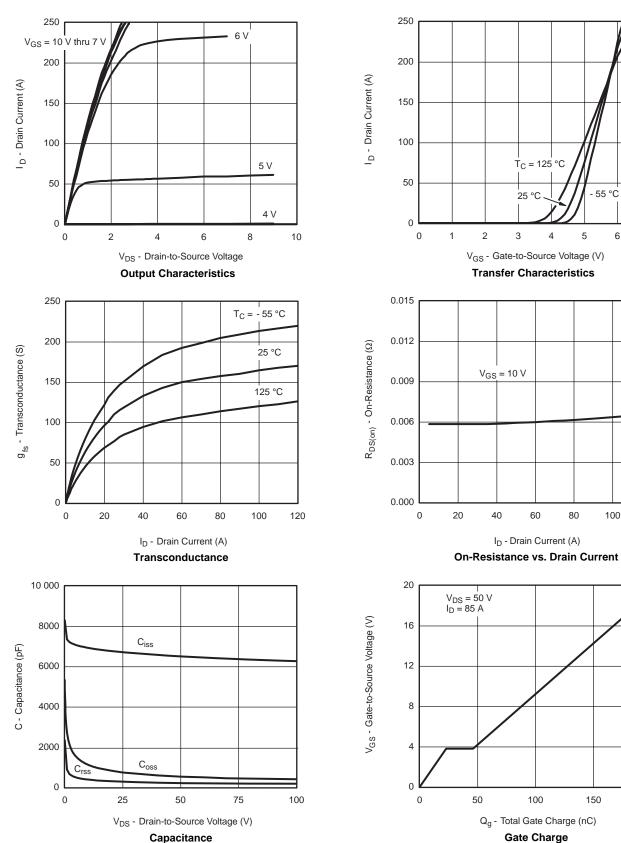
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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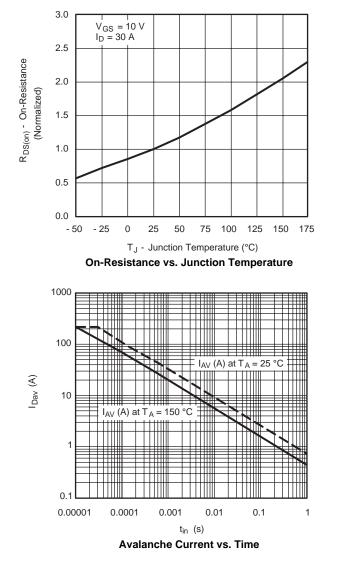
- 55 °C

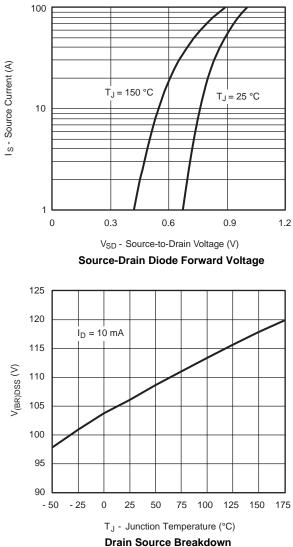


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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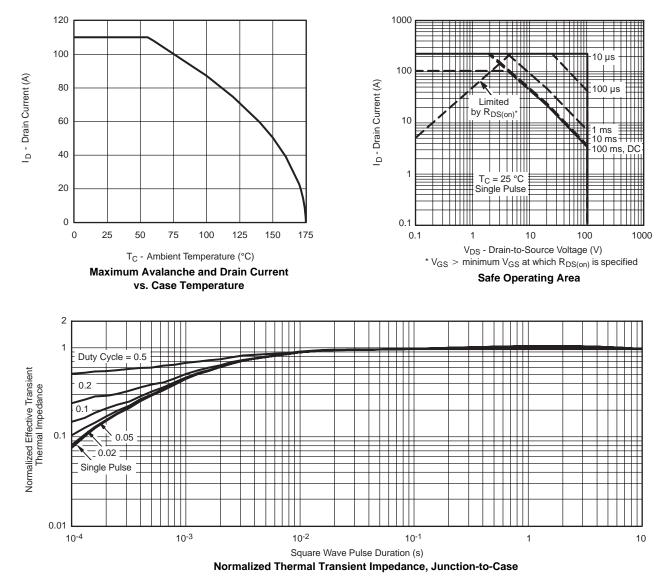


vs. Junction Temperature

HUF75652G3-VB

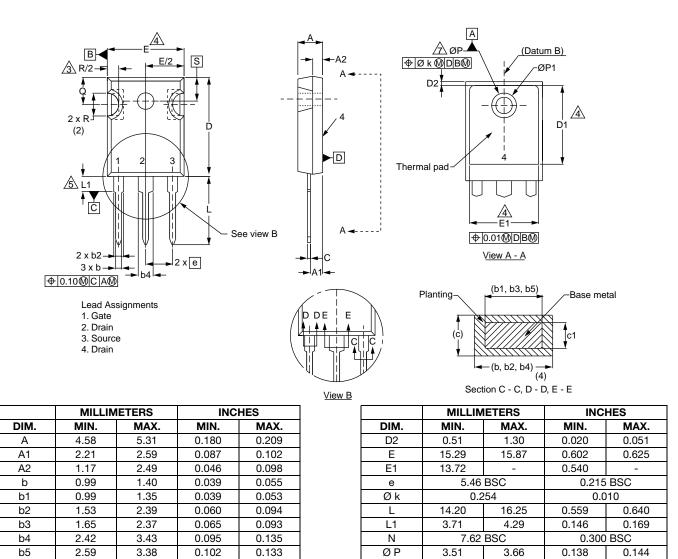


THERMAL RATINGS





TO-247AC



Ø P1

Q

R

S

5.31

4.52

0.291

0.224

0.216

7.39

5.69

5.49

5.51 BSC

0.209

0.178

0.217 BSC

0.38

0.38

19.71

13.08

0.86

0.76

20.82

-

0.015

0.015

0.776

0.515

0.034

0.030

0.820

С

с1

D

D1



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